**Preliminary Amendment** 

Applicant: Andrew Graham et al.

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Title: VERTICALLY INTEGRATED COMPONENT, COMPONENT ARRAY AND METHOD FOR

FABRICATING (As Amended)

## **IN THE ABSTRACT**

Please replace the Abstract with the following rewritten paragraph:

VERTICAL INTEGRATED COMPONENT, COMPONENT ARRANGEMENT AND
METHOD FOR PRODUCTION OF A VERTICAL INTEGRATED
COMPONENT VERTICALLY INTEGRATED COMPONENT, COMPONENT ARRAY
AND METHOD FOR FABRICATING

## **Abstract**

The invention relates to a vertical integrated component, a component arrangement and a method for production of a vertical integrated component. The vertical integrated component has a first electrical conducting layer—(101), a mid layer—(102), partly embodied from dielectric material on the first electrical conducting layer, a second electrical conducting layer—(103) on the mid layer and a nanostructure (104)—integrated in a through hold introduced in the mid layer—with aA first end section of the nanostructure is coupled to the first electrical conducting layer and a second end section is coupled to the second electrical conducting layer. The mid layer comprises includes a third electrical conducting layer (105) between two adjacent dielectric partial layers, (102a, 102b)—the thickness of which is less than the thickness of at least one of the dielectric partial layers.